ATTY DOCKET NO.: Q75814

AMENDMENT UNDER 37 C.F.R. § 1.114(c)

U.S. APPLN. NO.: 10/632,919

AMENDMENTS "O THE CLAIMS

This listing:of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1 (currently amended):—A compression bonding method in which an element is bonded to a substrate, the method comprising:

forming a laver having metal-on at least a part of a surface of the substrate;

disposing the element on the layer; and

bonding the element to the layer by applying pressure on the element toward the layer and irradiating light to which the element is transparent, on a bonding area between the element and the layer, The method of claim 11, wherein the light provides activating energy which allows an interactio to between the layer and the element approximately at room temperature.

- 2 (currently amended): The method of claim-111, wherein the element is formed of silica glass.
- 3 (currently amended): The method of claim-111, wherein the substrate is a silicon substrate.
- 4. (currently amended): A compression bonding-method-in-which an element is bonded to a substrate, the method comprising:

forming a layer having metal on at least a part of a surface of the substrate;

disposing the element on the layer; and

AMENDMENT UNDER 37 C.F.R. § 1.114(c)

ATTY DOCKET NO.: Q75814

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bonding the element to the layer by applying pressure on the element toward the layer and irradiating light to which the element is transparent, on a bonding area between the element and the layer The nethod of claim 11, wherein the light is irradiated on the bonding area for a predetermined time after the application of pressure.

- 5 (canceled).
- 6 (currently amended): The method of claim—1_11, wherein the light has a wavelength of not less than approximately 180 nm.
- 7 (currently amended): The method of claim-111, wherein the pressure, which acts at an interface between the layer and the element, ruptures a native oxide film on the layer and allows the element 10 contact a non-oxidized element of the layer.
 - 8 (canceled).
- 9. (currently amended): The method of claim-8_11, wherein a cross section of the element is round.
- 10. (currently amended): The method of claim-8_11, wherein the element is an optical element that is one cf a lens, an optical fiber, and a prism.

AMENDMENT UNDER 37 C.F.R. § 1.114(c)

ATTY DOCKET NO.: Q75814

U.S. APPLN. NO.: 10/632,919

(previously presented): A compression bonding method in which an element is 11. bonded to a substrate, the method comprising:

forming a layer having metal on at least a part of a surface of the substrate;

disposing the element on the layer; and

bonding the element to the layer by applying pressure on the element toward the layer and irradiating light to which the element is transparent, on a bonding area between the element and the layer, wherein the layer is a discontinuous layer.

- 12. (original): The method of claim 11, wherein the layer is formed as strips or dots.
- 13. (original): The method of claim 11, wherein a surface of the element which contacts the layer is substantially flat.

14-20 (canceled).

21. (currently amended): A compression-bonding method in which an element-is bonded to a substrate, the method comprising:

forming a layer having metal on at least a part of a surface of the substrate;

disposing the cloment on the layer; and

bonding the element to the layer by applying pressure on the element toward the layer and irradiating light to which the element is transparent, on a bonding area between the element and the layer The piethod of claim 11, wherein the light is substantially in the UV wavelength range.

AMENDMENT UNDER 37 C.F.R. § 1.114(c) U.S. APPLN. NO.: 10/632,919

ATTY DOCKET NO.: Q75814

22-24 (canceled).

- 25. (currently amended): The method of claim—1_11, wherein the metal includes aluminum.
- 26. (previously presented): The method of claim 7, wherein the non-oxidized element is aluminum.
 - 27. (canceled).